

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/08/2022

Details for "THS3001IDGNG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
THS3001IDGNG4	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DGN 8	3x3x1	26.9

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.01913	99.989546	999895	0.071125	711
Not Categorized	Proprietary Materials		0.000002	0.010454	105	0.000007	0
Sub-Total			0.019132	100	1000000	0.071132	711
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.151067	82.000022	820000	0.561662	5617
Thermoplastics	Epoxy	85954-11-6	0.033161	17.999978	180000	0.123291	1233
Sub-Total			0.184228	100	1000000	0.684953	6850
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	10.7408	95.9	959000	39.933921	399339
Magnesium and Its Alloys	Magnesium	7439-95-4	0.0196	0.175	1750	0.072872	729
Nickel and Its Alloys	Nickel	7440-02-0	0.3584	3.2	32000	1.332519	13325
Other inorganic Materials	Silicon	7440-21-3	0.0812	0.725	7250	0.301899	3019
Sub-Total			11.2	100	1000000	41.641211	416412
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.196157	97.299617	972996	0.729305	7293
Precious Metals	Gold	7440-57-5	0.000605	0.300098	3001	0.002249	22
Precious Metals	Palladium	7440-05-3	0.004234	2.100188	21002	0.015742	157
Precious Metals	Silver	7440-22-4	0.000605	0.300098	3001	0.002249	22
Sub-Total			0.201601	100	1000000	0.749546	7495
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	13.398418	93.499999	935000	49.814853	498149
Other Plastics and Rubber	Carbon Black	1333-86-4	0.071649	0.499998	5000	0.266388	2664
Thermoplastics	Epoxy	85954-11-6	0.859792	6.000003	60000	3.196677	31967
Sub-Total			14.329859	100	1000000	53.277918	532779
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.961612	100	1000000	3.57524	35752
Sub-Total			0.961612	100	1000000	3.57524	35752
Total			26.896432			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet I5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.